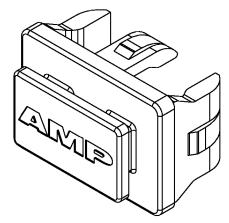
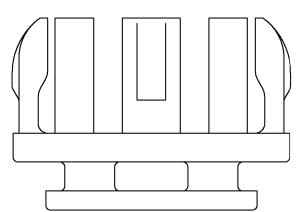


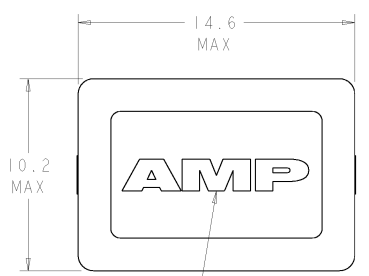
THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION BY TICO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED. © COPYRIGHT 2000

REV	DATE	BY	CHKD	DESCRIPTION
0	09022000	DB	RF	PLSE PER EC 0010-0250-00
A	09062000	DB	RF	REV PER EC 0010-0277-00
B	08022001	DB	JK	OBS -2 PER EC 0010-0289-00
C	120601	JG	JK	REVISED PER EC 0513-0065-01

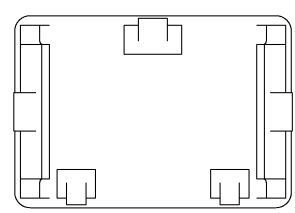
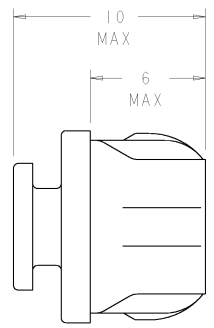


SCALE 5:1

- △ THERMOPLASTIC MOLDING COMPOUND.
- △ TIN PLATING OVER COPPER PLATING.
- △ OBSOLETE.



AMP LOGO FOR -1 & -2



NO	-	△	1367147-3
YES	△	1367147-1	△ 1367147-2
YES	-	△	1367147-1
AMP LOGO	FINISH	MATERIAL	PART NUMBER

DIMENSIONS: mm		DIMENSIONS AND FINISH SPECIFICATIONS: D PLC - H PLC - R PLC - F PLC - ANGLE: - FINISH: -		DAN 30AUG2000 CHD - KRLH 30AUG2000 AYO - BRIGHT 30AUG2000 AYO - BRIGHT 30AUG2000	TICO Electronics Harrisburg, PA 17105-3608
MATERIAL: SEE TABLE		FINISH: SEE TABLE		PRODUCT SPEC: - APPLICATION SPEC: - WEIGHT: -	COVER, SFP SIZE: A2 CASE CODE: C=1367147 DRAWING NO: - RESTRICTED TO: -
CUSTOMER DRAWING				SCALE: 7:1 SHEET 1 OF 1 REV C	TICO Electronics Harrisburg, PA 17105-3608